

PATENT  
TESSERA 3.0-078 DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of  
Joseph Fjelstad

Divisional of Application No. 08/739,303  
filed October 29, 1996

Filed: Herewith

For: Semiconductor Chip Package  
With Fan-In Leads

Group Art Unit:

Examiner:

Date: February 9, 1998

Assistant Commissioner For Patents  
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

After according a filing date to the above-identified Rule 53(b)

Divisional Application, please amend the application as follows:

In the Claims

Cancel claims 12-20.

In the Title

Please amend the title of the application to --Method of Making a  
Semiconductor Chip Package--.

In the Specification

Page I, before line 1, insert --This is a divisional of United States  
Patent Application Serial No. 08/739,303 filed October 29, 1996 the benefit of  
which is claimed under 35 U.S.C. § 120.--.

Abstract of the Disclosure

Please cancel the abstract presently on file and substitute  
therefore the following:

--Abstract of the Disclosure

EXPRESS MAIL LABEL NUMBER: EM176698854US

A method of making a compliant semiconductor chip package assembly includes providing a first dielectric protective layer on a contact bearing surface of a semiconductor chip wherein the semiconductor chip has a central region bounded by chip contacts of the semiconductor chip and wherein the dielectric protective layer has a plurality of apertures so that the chip contacts are exposed; providing a compliant layer atop the first dielectric protective layer within the central region wherein the compliant layer has a substantially flat top surface, a bottom surface that is attached to the first dielectric protective layer and sloping edges between the top surface and the bottom surface; and selectively electroplating bond ribbons atop the first dielectric protective layer in the compliant layer wherein each bond ribbon electrically connects each chip contact to a respective conductive terminal on the top surface of the compliant layer.—

Remarks

The present application is a divisional of U. S. Patent Application Serial No. 08/739,303, filed October 29, 1996 and is in response to a restriction requirement of the Examiner in the '303 application. The present application is directed to the non-elected claims of the '303 application. The present Preliminary Amendment cancels claims 12-20 and amends the title and the abstract to more accurately describe the scope of the presently claimed invention.

The present Preliminary Amendment should be entered because it is fully supported by the specification and introduces no new matter.

For all of the reasons set forth above, prompt and favorable consideration of the amended application and allowance of claims 1-11 is respectively requested.

Respectfully submitted,

LERNER, DAVID, LITTENBERG  
KRUMHOLZ & MENTLIK

*Michael J. Doherty*

MICHAEL J. DOHERTY  
Reg. No. 40,592

600 South Avenue West  
Westfield, New Jersey 07090  
(908) 654-5000 - Telephone  
(908) 654-7866 - Facsimile